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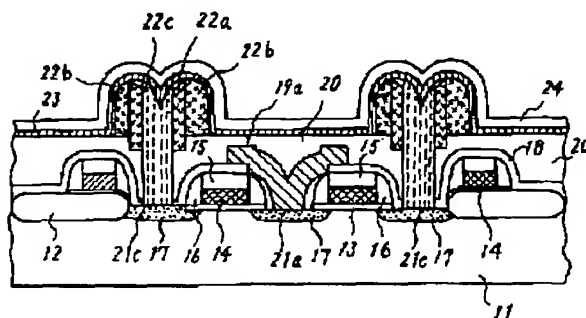
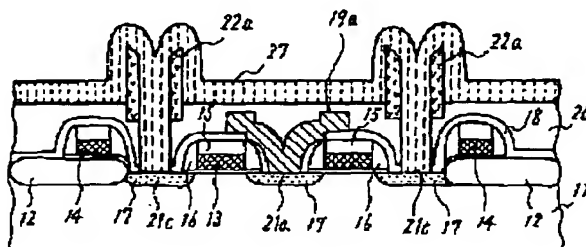
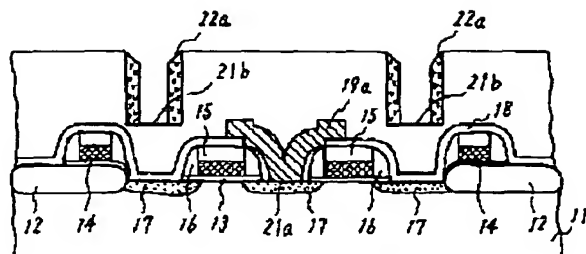
APPLICATION NUMBER : 06031443

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TITLE : MANUFACTURE OF
SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To decrease the number of photolithography processes and realize cost reduction, by depositing first conducting material so as to cover the peripheral part of a protruding frame part, etching back the first conducting material, and covering the etched-back first conducting material and a dielectric film with second conducting material.

CONSTITUTION: A first aperture 21b is formed in an insulating film 20, and a frame part 22a is formed on the side wall of the first aperture 21b. By etching back the whole part of the insulating film 20, a second aperture 21c is formed below the first aperture 21b, and the frame part 22a is made to protrude from the edge end portion of the second aperture 21c. First conducting material 27 is deposited on the insulating film 20 so as to cover the peripheral part of a protruding frame part 22 and be electrically connected with the bottom part of the second aperture 21c. The first conducting material 27 is etched back, and the first conducting material 27 after etched back is covered with a dielectric film 23, which is covered with second conducting material 24.

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